

RECEIVED  
CENTRAL FAX CENTER

SEP 23 2009

PATENT  
YOR920030206US1

## IN THE UNITED STATES PATENT &amp; TRADEMARK OFFICE

In re Application of	:	Lawrence Shungwei Mok
Serial Number	:	10/784,624
Filing Date	:	02/23/2004
Examiner	:	Tho V. Duong
Group Art Unit	:	3744
For	:	HEAT DISSIPATION INTERFACE FOR SEMICONDUCTOR CHIP STRUCTURES

Sir:

In response to the Official Action dated June 23, 2009, please amend the above-identified application as follows:

## In the Claims:

Cancel Claims 10 and 11 and add new Claims 12 –20 therefore; and amend Claims 1, 3 and 4, all as set forth in the Appendix A attached hereto.

## REMARKS

Applicant has amended Claims 3 and 4 to make them dependent upon Claim 1. Claims 11 and 12 have been canceled to obviate the rejection under 35 U.S.C. §112, first paragraph. Claim 1 has been amended in a good faith effort to obviate the rejections under 35 U.S.C. §112, second paragraph.